

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

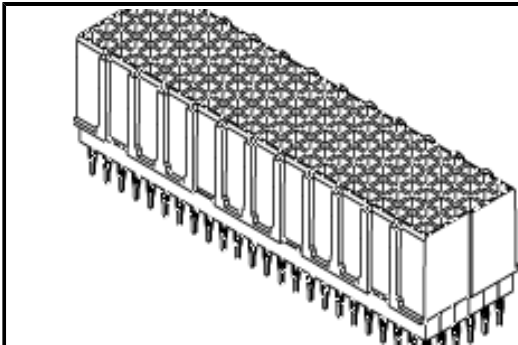
Part Number: [0737800257](#)
Status: **Active**
Overview: [HDM Backplane Connector System](#)
Description: HDM Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 72 Circuits, Mounted Height 17.00mm, Pin Length 3.50mm, Solder Tail

Documents:
[3D Model](#)
[Drawing \(PDF\)](#)
[Product Specification PS-73780-999-001 \(PDF\)](#)
[Packaging Specification PK-70873-0872 \(PDF\)](#)
[Test Summary TS-73670-990-001 \(PDF\)](#)
[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification
UL E29179

General
Product Family Backplane Connectors
Series [73780](#)
Application Daughtercard, Mezzanine
Comments Solder Tail, Solder Tail
Component Type PCB Receptacle
Overview [HDM Backplane Connector System](#)
Product Name HDM
UPC 800756201122

Physical
Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Copper-Nickel-Tin
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
Net Weight 10.002/g
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length 3.50mm
PCB Locator No
PCB Retention None
PCB Thickness - Recommended 1.60mm
Packaging Type Tube
Pitch - Mating Interface 2.00mm
Pitch - Termination Interface 2.00mm
Plating min - Mating 0.762µm
Plating min - Termination 2.540µm
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55° to +105°C
Termination Interface: Style Through Hole



Series image - Reference only

EU ELV
Not Relevant

EU RoHS **China RoHS**
Compliant
REACH SVHC
Not Contained Per -
ED/71/2019 (16 July
2019)
Halogen-Free
Status
Low-Halogen

For more information, please visit [Contact US](#)

China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series
[73780](#) Series

Mates With
HDM Board-to-Board Backplane Header
[73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) ,
[73944](#) , [74349](#) , [74428](#). HDM Board-to-
Board Stacking Header [73769](#) , [73770](#) ,
[73782](#) , [73783](#) , [73771](#)

Electrical

Current - Maximum per Contact	15.0A, 1.0A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	005
Lead-freeProcess Capability	WAVE
Max. Cycles at Max. Process Temperature	001
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0872
Product Specification	PS-73780-999-001
Sales Drawing	SD-73780-004
Test Summary	TS-73670-990-001

This document was generated on 09/16/2019

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Molex:](#)

[73780-0257](#)